

描述 / Descriptions

快恢复二极管，反向电压：50V~1000V，正向电流：3.0A，薄型 SMAF 封装。

Surface Mount Fast Recovery Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:3.0A ,SMAF thin package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途 / Applications

一般用途.

General purpose.

内部等效电路 / Equivalent Circuit

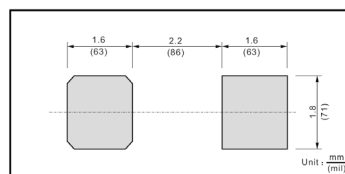


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3AF	S3BF	S3DF	S3GF	S3JF	S3KF	S3MF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	90							A
Typical Junction Capacitance at VR=4V f=1MHz	C_j	45							pF
Typical Thermal Resistance ¹⁾	$R_{\theta JA}$	47							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150							°C

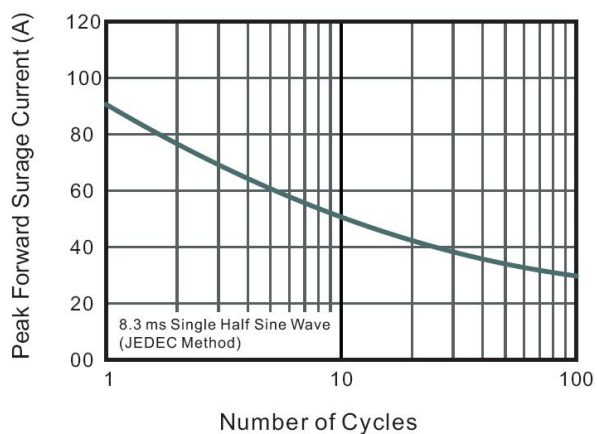
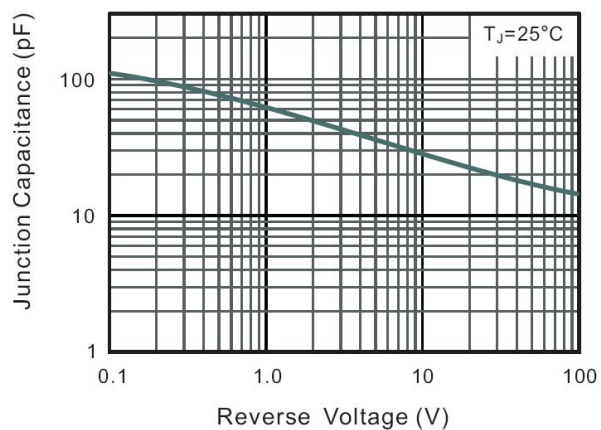
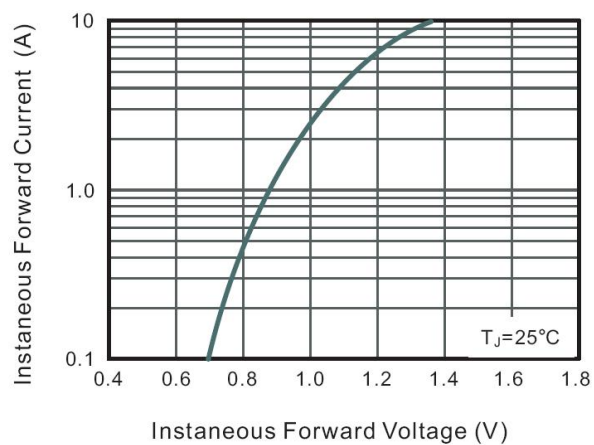
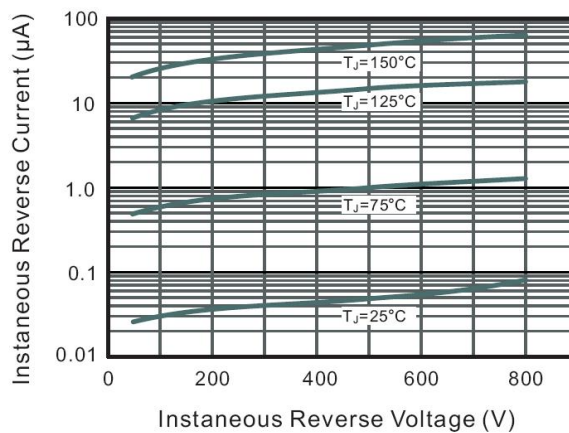
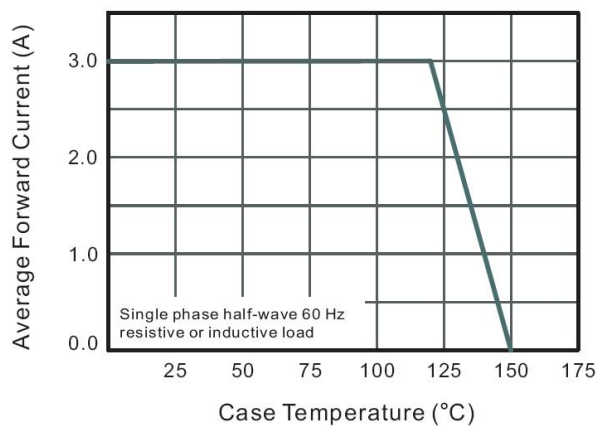
Note:

1) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 mm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

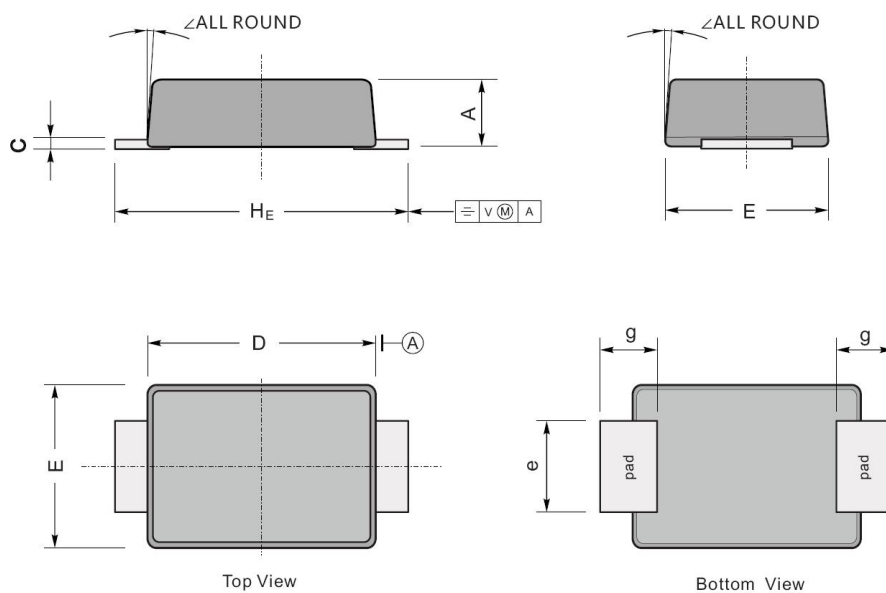
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S3AF	S3BF	S3DF	S3GF	S3JF	S3KF	S3MF	
Maximum Instantaneous Forward Voltage	V_F	$I_F=3.0A$	1.2							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^{\circ}C$	5.0							μA
		$T_a=125^{\circ}C$	125							μA

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SMAF

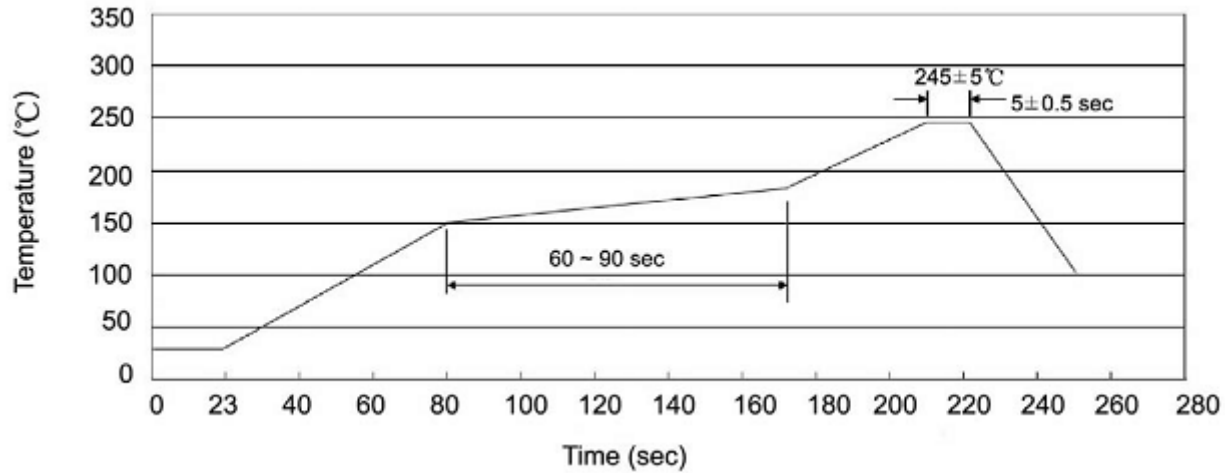


UNIT		A	C	D	E	e	g	H_E	$\angle$
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	43	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

Marking

Type number	Marking code
S3AF	S3A
S3BF	S3B
S3DF	S3D
S3GF	S3G
S3JF	S3J
S3KF	S3K
S3MF	S3M

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMAF	3000	5	15000	5	75000	7" ×11	185X180X105	550X210X220

使用说明 / Notices